

# BZX84BxxxLT1, BZX84CxxxLT1 Series, SZBZX84BxxxLT1G, SZBZX84CxxxLT1G Series



## Zener Voltage Regulators

### 225 mW SOT-23 Surface Mount

This series of Zener diodes is offered in the convenient, surface mount plastic SOT-23 package. These devices are designed to provide voltage regulation with minimum space requirement. They are well suited for applications such as cellular phones, hand held portables, and high density PC boards.

#### Features

- 225 mW Rating on FR-4 or FR-5 Board
- Zener Breakdown Voltage Range – 2.4 V to 75 V
- Package Designed for Optimal Automated Board Assembly
- Small Package Size for High Density Applications
- ESD Rating of Class 3 (>16 kV) per Human Body Model
- Tight Tolerance Series Available (See Page 4)
- AEC-Q101 Qualified and PPAP Capable
- SZ Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- Pb-Free Packages are Available

#### Mechanical Characteristics

**CASE:** Void-free, transfer-molded, thermosetting plastic case

**FINISH:** Corrosion resistant finish, easily Solderable

**MAXIMUM CASE TEMPERATURE FOR SOLDERING PURPOSES:**  
260°C for 10 Seconds

**POLARITY:** Cathode indicated by polarity band

**FLAMMABILITY RATING:** UL 94 V-0

#### MAXIMUM RATINGS

Rating	Symbol	Max	Unit
Total Power Dissipation on FR-5 Board, (Note 1) @ T <sub>A</sub> = 25°C Derated above 25°C	P <sub>D</sub>	225	mW
Thermal Resistance, Junction-to-Ambient	R <sub>θJA</sub>	1.8 556	mW/°C °C/W
Total Power Dissipation on Alumina Substrate, (Note 2) @ T <sub>A</sub> = 25°C Derated above 25°C	P <sub>D</sub>	300	mW
Thermal Resistance, Junction-to-Ambient	R <sub>θJA</sub>	2.4 417	mW/°C °C/W
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-65 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. FR-5 = 1.0 X 0.75 X 0.62 in.
2. Alumina = 0.4 X 0.3 X 0.024 in., 99.5% alumina.

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#### MARKING DIAGRAM



xxx = Device Code  
M = Date Code\*  
▪ = Pb-Free Package

(Note: Microdot may be in either location)

\*Date Code orientation may vary depending upon manufacturing location.

#### ORDERING INFORMATION

Device	Package	Shipping†
BZX84CxxxLT1	SOT-23	3000/Tape & Reel
BZX84CxxxLT1G	SOT-23 (Pb-Free)	3000/Tape & Reel
SZBZX84xxxLT1G	SOT-23 (Pb-Free)	3000/Tape & Reel
BZX84CxxxLT3	SOT-23	10,000/Tape & Reel
BZX84CxxxLT3G	SOT-23 (Pb-Free)	10,000/Tape & Reel
SZBZXCxxxLT3G	SOT-23 (Pb-Free)	10,000/Tape & Reel
BZX84BxxxLT1	SOT-23	3000/Tape & Reel
BZX84BxxxLT1G	SOT-23 (Pb-Free)	3000 / Tape & Reel
SZBZX84BxxxLT1G	SOT-23 (Pb-Free)	3000 / Tape & Reel
BZX84BxxxLT3	SOT-23	10,000 / Tape & Reel
BZX84BxxxLT3G	SOT-23 (Pb-Free)	10,000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

#### DEVICE MARKING INFORMATION

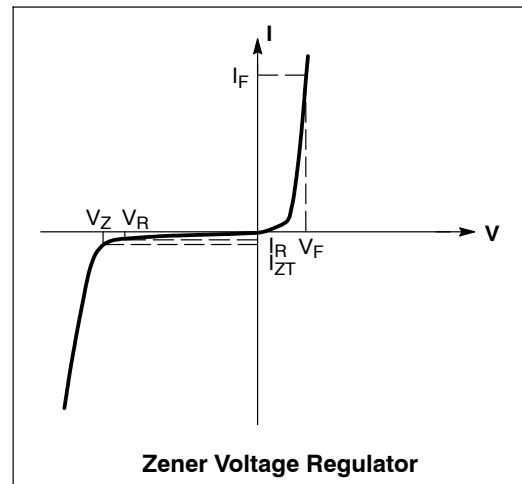
See specific marking information in the device marking column of the Electrical Characteristics table on page 3 of this data sheet.

# BZX84BxxxLT1, BZX84CxxxLT1 Series, SZBZX84BxxxLT1G, SZBZX84CxxxLT1G Series

## ELECTRICAL CHARACTERISTICS

(Pinout: 1-Anode, 2-No Connection, 3-Cathode) ( $T_A = 25^\circ\text{C}$  unless otherwise noted,  $V_F = 0.90\text{ V Max. @ } I_F = 10\text{ mA}$ )

Symbol	Parameter
$V_Z$	Reverse Zener Voltage @ $I_{ZT}$
$I_{ZT}$	Reverse Current
$Z_{ZT}$	Maximum Zener Impedance @ $I_{ZT}$
$I_R$	Reverse Leakage Current @ $V_R$
$V_R$	Reverse Voltage
$I_F$	Forward Current
$V_F$	Forward Voltage @ $I_F$
$\Theta V_Z$	Maximum Temperature Coefficient of $V_Z$
C	Max. Capacitance @ $V_R = 0$ and $f = 1\text{ MHz}$



# BZX84BxxxLT1, BZX84CxxxLT1 Series, SZBZX84BxxxLT1G, SZBZX84CxxxLT1G Series

## ELECTRICAL CHARACTERISTICS – BZX84CxxxLT1 SERIES (STANDARD TOLERANCE)

(Pinout: 1-Anode, 2-No Connection, 3-Cathode) (T<sub>A</sub> = 25°C unless otherwise noted, V<sub>F</sub> = 0.90 V Max. @ I<sub>F</sub> = 10 mA)  
(Devices listed in **bold, italic** are ON Semiconductor Preferred devices.)

Device*	Device Marking	V <sub>Z1</sub> (Volts) @ I <sub>ZT1</sub> = 5 mA (Note 3)			Z <sub>ZT1</sub> (Ω) @ I <sub>ZT1</sub> = 5 mA	V <sub>Z2</sub> (V) @ I <sub>ZT2</sub> = 1 mA (Note 3)		Z <sub>ZT2</sub> (Ω) @ I <sub>ZT2</sub> = 1 mA	V <sub>Z3</sub> (V) @ I <sub>ZT3</sub> = 20 mA (Note 3)		Z <sub>ZT3</sub> (Ω) @ I <sub>ZT3</sub> = 20 mA	Max Reverse Leakage Current		θ <sub>VZ</sub> (mV/k) @ I <sub>ZT1</sub> = 5 mA		C (pF) @ V <sub>R</sub> = 0 f = 1 MHz
		Min	Nom	Max		Min	Max		Min	Max		I <sub>R</sub> μA	V <sub>R</sub> Volts	Min	Max	
SZ/BZX84C2V4LT1, G	Z11	2.2	2.4	2.6	100	1.7	2.1	600	2.6	3.2	50	50	1	-3.5	0	450
SZ/BZX84C2V7LT1, G	Z12	2.5	2.7	2.9	100	1.9	2.4	600	3	3.6	50	20	1	-3.5	0	450
SZ/BZX84C3V0LT1, G	Z13	2.8	3	3.2	95	2.1	2.7	600	3.3	3.9	50	10	1	-3.5	0	450
SZ/BZX84C3V3LT1, G	Z14	3.1	3.3	3.5	95	2.3	2.9	600	3.6	4.2	40	5	1	-3.5	0	450
SZ/BZX84C3V6LT1, G	Z15	3.4	3.6	3.8	90	2.7	3.3	600	3.9	4.5	40	5	1	-3.5	0	450
SZ/BZX84C3V9LT1, G	Z16	3.7	3.9	4.1	90	2.9	3.5	600	4.1	4.7	30	3	1	-3.5	-2.5	450
SZ/BZX84C4V3LT1, G	W9	4	4.3	4.6	90	3.3	4	600	4.4	5.1	30	3	1	-3.5	0	450
<b>SZ/BZX84C4V7LT1/T3, G</b>	<b>Z1</b>	<b>4.4</b>	<b>4.7</b>	<b>5</b>	<b>80</b>	<b>3.7</b>	<b>4.7</b>	<b>500</b>	<b>4.5</b>	<b>5.4</b>	<b>15</b>	<b>3</b>	<b>2</b>	<b>-3.5</b>	<b>0.2</b>	<b>260</b>
<b>SZ/BZX84C5V1LT1/T3, G</b>	<b>Z2</b>	<b>4.8</b>	<b>5.1</b>	<b>5.4</b>	<b>60</b>	<b>4.2</b>	<b>5.3</b>	<b>480</b>	<b>5</b>	<b>5.9</b>	<b>15</b>	<b>2</b>	<b>2</b>	<b>-2.7</b>	<b>1.2</b>	<b>225</b>
<b>SZ/BZX84C5V6LT1/T3, G</b>	<b>Z3</b>	<b>5.2</b>	<b>5.6</b>	<b>6</b>	<b>40</b>	<b>4.8</b>	<b>6</b>	<b>400</b>	<b>5.2</b>	<b>6.3</b>	<b>10</b>	<b>1</b>	<b>2</b>	<b>-2.0</b>	<b>2.5</b>	<b>200</b>
<b>SZ/BZX84C6V2LT1/T3, G</b>	<b>Z4</b>	<b>5.8</b>	<b>6.2</b>	<b>6.6</b>	<b>10</b>	<b>5.6</b>	<b>6.6</b>	<b>150</b>	<b>5.8</b>	<b>6.8</b>	<b>6</b>	<b>3</b>	<b>4</b>	<b>0.4</b>	<b>3.7</b>	<b>185</b>
SZ/BZX84C6V8LT1/T3, G	Z5	6.4	6.8	7.2	15	6.3	7.2	80	6.4	7.4	6	2	4	1.2	4.5	155
SZ/BZX84C7V5LT1, G	Z6	7	7.5	7.9	15	6.9	7.9	80	7	8	6	1	5	2.5	5.3	140
SZ/BZX84C8V2LT1, G	Z7	7.7	8.2	8.7	15	7.6	8.7	80	7.7	8.8	6	0.7	5	3.2	6.2	135
SZ/BZX84C9V1LT1/T3, G	Z8	8.5	9.1	9.6	15	8.4	9.6	100	8.5	9.7	8	0.5	6	3.8	7.0	130
SZ/BZX84C10LT1, G	Z9	9.4	10	10.6	20	9.3	10.6	150	9.4	10.7	10	0.2	7	4.5	8.0	130
SZ/BZX84C11LT1, G	Y1	10.4	11	11.6	20	10.2	11.6	150	10.4	11.8	10	0.1	8	5.4	9.0	130
<b>SZ/BZX84C12LT1, G</b>	<b>Y2</b>	<b>11.4</b>	<b>12</b>	<b>12.7</b>	<b>25</b>	<b>11.2</b>	<b>12.7</b>	<b>150</b>	<b>11.4</b>	<b>12.9</b>	<b>10</b>	<b>0.1</b>	<b>8</b>	<b>6.0</b>	<b>10.0</b>	<b>130</b>
SZ/BZX84C13LT1, G	Y3	12.4	13	14.1	30	12.3	14	170	12.5	14.2	15	0.1	8	7.0	11.0	120
SZ/BZX84C15LT1/T3, G	Y4	13.8	15	15.6	30	13.7	15.5	200	13.9	15.7	20	0.05	10.5	9.2	13.0	110
SZ/BZX84C16LT1, G	Y5	15.3	16	17.1	40	15.2	17	200	15.4	17.2	20	0.05	11.2	10.4	14.0	105
<b>SZ/BZX84C18LT1/T3, G</b>	<b>Y6</b>	<b>16.8</b>	<b>18</b>	<b>19.1</b>	<b>45</b>	<b>16.7</b>	<b>19</b>	<b>225</b>	<b>16.9</b>	<b>19.2</b>	<b>20</b>	<b>0.05</b>	<b>12.6</b>	<b>12.4</b>	<b>16.0</b>	<b>100</b>
SZ/BZX84C20LT1, G	Y7	18.8	20	21.2	55	18.7	21.1	225	18.9	21.4	20	0.05	14	14.4	18.0	85
SZ/BZX84C22LT1, G	Y8	20.8	22	23.3	55	20.7	23.2	250	20.9	23.4	25	0.05	15.4	16.4	20.0	85
SZ/BZX84C24LT1, G	Y9	22.8	24	25.6	70	22.7	25.5	250	22.9	25.7	25	0.05	16.8	18.4	22.0	80
Device	Device Marking	V <sub>Z1</sub> Below @ I <sub>ZT1</sub> = 2 mA			Z <sub>ZT1</sub> Below @ I <sub>ZT1</sub> = 2 mA	V <sub>Z2</sub> Below @ I <sub>ZT2</sub> = 0.1 m- A		Z <sub>ZT2</sub> Below @ I <sub>ZT2</sub> = 0.5 mA	V <sub>Z3</sub> Below @ I <sub>ZT3</sub> = 10 mA		Z <sub>ZT3</sub> Below @ I <sub>ZT3</sub> = 10 mA	Max Reverse Leakage Current		θ <sub>VZ</sub> (mV/k) Below @ I <sub>ZT1</sub> = 2 mA		C (pF) @ V <sub>R</sub> = 0 f = 1 MHz
		Min	Nom	Max		Min	Max		Min	Max		I <sub>R</sub> μA	V <sub>R</sub> (V)	Min	Max	
SZ/BZX84C27LT1, G	Y10	25.1	27	28.9	80	25	28.9	300	25.2	29.3	45	0.05	18.9	21.4	25.3	70
SZ/BZX84C30LT1, G	Y11	28	30	32	80	27.8	32	300	28.1	32.4	50	0.05	21	24.4	29.4	70
SZ/BZX84C33LT1/T3, G	Y12	31	33	35	80	30.8	35	325	31.1	35.4	55	0.05	23.1	27.4	33.4	70
SZ/BZX84C36LT1, G	Y13	34	36	38	90	33.8	38	350	34.1	38.4	60	0.05	25.2	30.4	37.4	70
SZ/BZX84C39LT1, G	Y14	37	39	41	130	36.7	41	350	37.1	41.5	70	0.05	27.3	33.4	41.2	45
SZ/BZX84C43LT1, G	Y15	40	43	46	150	39.7	46	375	40.1	46.5	80	0.05	30.1	37.6	46.6	40
SZ/BZX84C47LT1, G	Y16	44	47	50	170	43.7	50	375	44.1	50.5	90	0.05	32.9	42.0	51.8	40
SZ/BZX84C51LT1, G	Y17	48	51	54	180	47.6	54	400	48.1	54.6	100	0.05	35.7	46.6	57.2	40
SZ/BZX84C56LT1, G	Y18	52	56	60	200	51.5	60	425	52.1	60.8	110	0.05	39.2	52.2	63.8	40
SZ/BZX84C62LT1, G	Y19	58	62	66	215	57.4	66	450	58.2	67	120	0.05	43.4	58.8	71.6	35
SZ/BZX84C68LT1, G	Y20	64	68	72	240	63.4	72	475	64.2	73.2	130	0.05	47.6	65.6	79.8	35
SZ/BZX84C75LT1, G	Y21	70	75	79	255	69.4	79	500	70.3	80.2	140	0.05	52.5	73.4	88.6	35

3. Zener voltage is measured with a pulse test current I<sub>Z</sub> at an ambient temperature of 25°C.

\*The "G" suffix indicates Pb-Free package available.

# BZX84BxxxLT1, BZX84CxxxLT1 Series, SZBZX84BxxxLT1G, SZBZX84CxxxLT1G Series

## ELECTRICAL CHARACTERISTICS – BZX84BxxxL (Tight Tolerance Series)

(Pinout: 1-Anode, 2-No Connection, 3-Cathode) ( $T_A = 25^\circ\text{C}$  unless otherwise noted,  $V_F = 0.90\text{ V Max. @ } I_F = 10\text{ mA}$ )

Device	Device Marking	$V_Z$ (Volts) @ $I_{ZT} = 5\text{ mA}$ (Note 4)			$Z_{ZT} (\Omega)$ @ $I_{ZT} = 5\text{ mA}$ (Note 4)	Max Reverse Leakage Current		$\theta_{VZ}$ (mV/k) @ $I_{ZT} = 5\text{ mA}$		C (pF) @ $V_R = 0$ , f = 1 MHz
						$I_R$	$V_R$			
		Min	Nom	Max	Max	$\mu\text{A}$	@ Volts	Min	Max	
BZX84B4V7LT1, G	T10	4.61	4.7	4.79	80	3	2	-3.5	0.2	260
SZ/BZX84B5V1LT1, G	T11	5.00	5.1	5.20	60	2	2	-2.7	1.2	225
SZ/BZX84B5V6LT1, G	T12	5.49	5.6	5.71	40	1	2	-2	2.5	200
SZ/BZX84B6V2LT1, G	T13	6.08	6.2	6.32	10	3	4	0.4	3.7	185
SZ/BZX84B6V8LT1, G	T14	6.66	6.8	6.94	15	2	4	1.2	4.5	155
SZ/BZX84B7V5LT1, G	T15	7.35	7.5	7.65	15	1	5	2.5	5.3	140
BZX84B8V2LT1, G	T16	8.04	8.2	8.36	15	0.7	5	3.2	6.2	135
BZX84B9V1LT1, G	T17	8.92	9.1	9.28	15	0.5	6	3.8	7	130
SZ/BZX84B12LT1, G	T18	11.8	12	12.2	25	0.1	8	6	10	130
BZX84B15LT1, G	T22	14.7	15	15.3	30	0.05	10.5	9.2	13	110
SZ/BZX84B16LT1, G	T19	15.7	16	16.3	40	0.05	11.2	10.4	14	105
BZX84B18LT1, G	T20	17.6	18	18.4	45	0.05	12.6	12.4	16	100
BZX84B22LT1, G	T24	21.6	22	22.4	55	0.05	15.4	16.4	20	85
BZX84B24LT1, G	T25	23.5	24	24.5	70	0.05	16.8	18.4	22	80

4. Zener voltage is measured with a pulse test current  $I_Z$  at an ambient temperature of  $25^\circ\text{C}$ .

\*The "G" suffix indicates Pb-Free package available.

TYPICAL CHARACTERISTICS

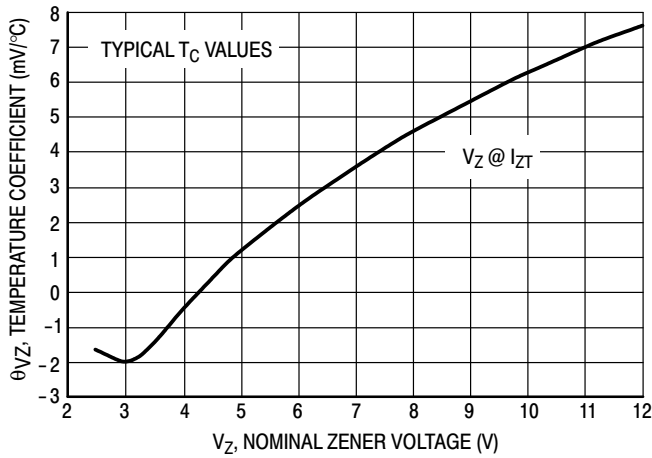


Figure 1. Temperature Coefficients (Temperature Range -55°C to +150°C)

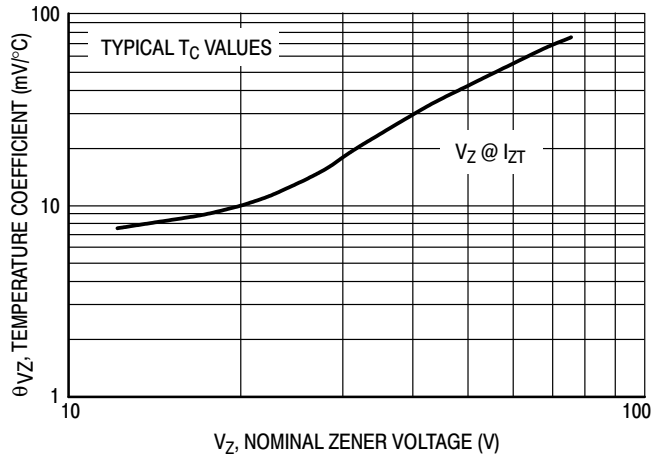


Figure 2. Temperature Coefficients (Temperature Range -55°C to +150°C)

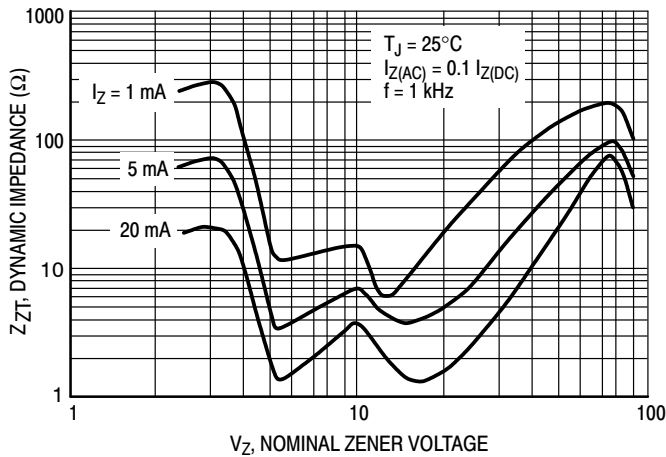


Figure 3. Effect of Zener Voltage on Zener Impedance

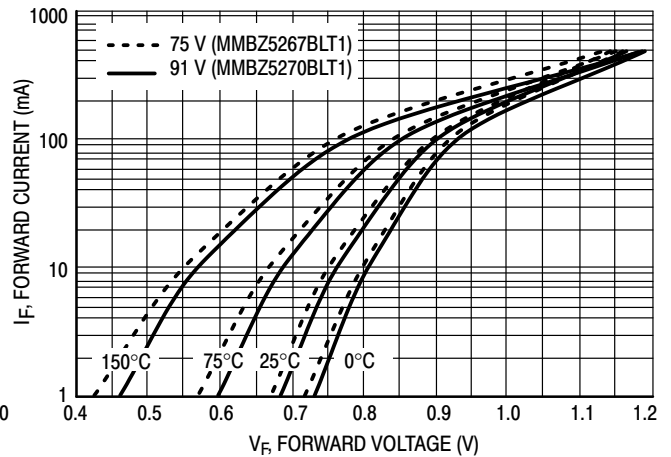


Figure 4. Typical Forward Voltage

TYPICAL CHARACTERISTICS

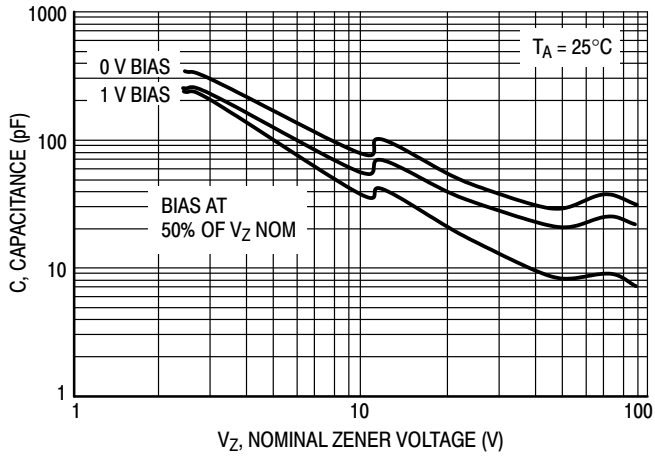


Figure 5. Typical Capacitance

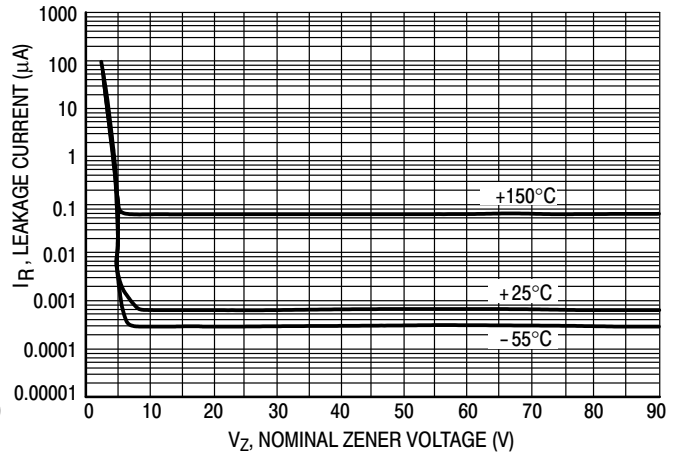


Figure 6. Typical Leakage Current

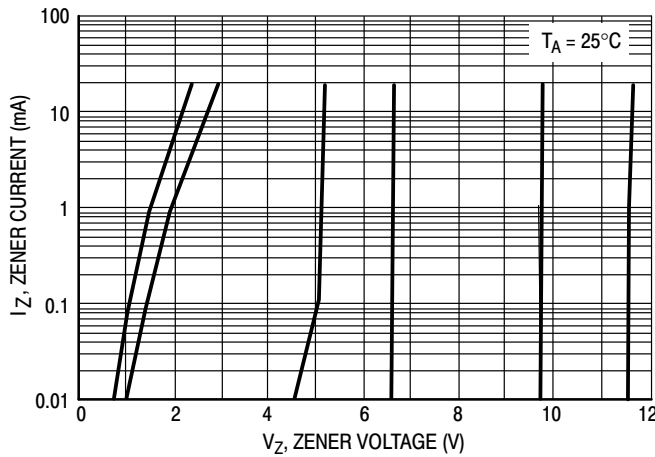


Figure 7. Zener Voltage versus Zener Current ( $V_Z$  Up to 12 V)

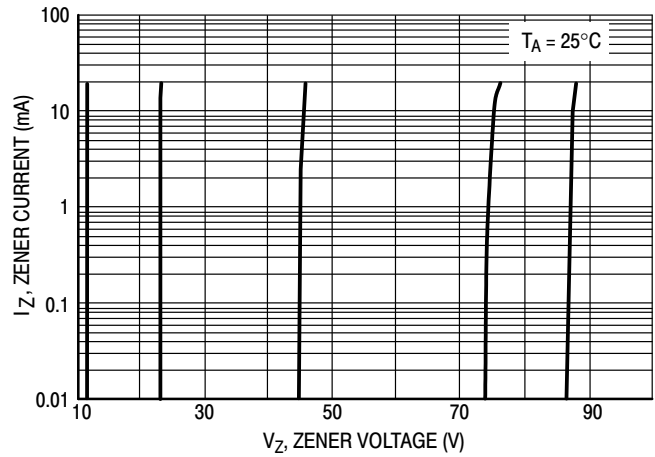
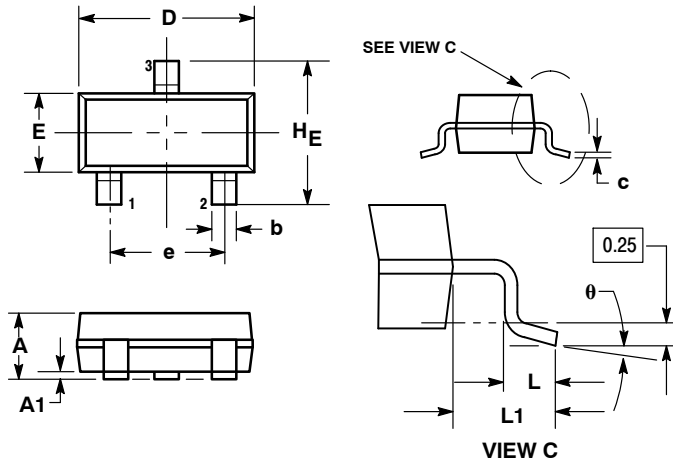


Figure 8. Zener Voltage versus Zener Current (12 V to 91 V)

# BZX84BxxxLT1, BZX84CxxxLT1 Series, SZBZX84BxxxLT1G, SZBZX84CxxxLT1G Series

## PACKAGE DIMENSIONS

### SOT-23 (TO-236) CASE 318-08 ISSUE AP



#### NOTES:

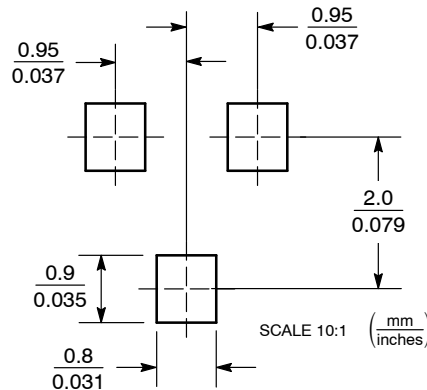
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
c	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
e	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.40	2.64	0.083	0.094	0.104
θ	0°	---	10°	0°	---	10°


#### STYLE 8:

1. ANODE
2. NO CONNECTION
3. CATHODE

### SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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